# Chip Bead Cores

Type: EXCCL EXCML EXC3B



#### ■ Features

- Effective noise suppression for Power line and high speed signal line.
- Easy pattern layout on PC Board without jointing the ground pattern.
- Available for flow soldering and re-flow soldering.

### Type: EXCCL, EXCML

- Low DC Resistance 3 to 8 mil ohm typical: Rated current 3, 4 ampere for Power line (type EXCML)
- Low impedance: the wave-form correction for high speed signal line noise

#### Type: EXC3B

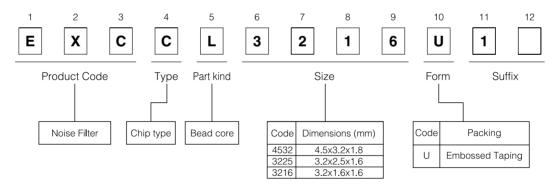
- High impedance for high speed signal line noise
- To increase attenuation by raising the R component steeply from around 50 MHz.
- $60\Omega$ -1A,  $120\Omega$ -0.5A are achieved by 1608 size. (type: EXC3BP)

### ■ Recommended Applications

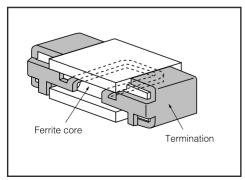
- Digital equipment such as Personal Computers, Word Processors, Printer, HDD, PCC, CD-ROM, DVD-ROM
- Digital Audio and Video equipment such as VCR, DVC, CD Player, DVD Player.
- Power supply equipment such as AC adapter, and Switching Power Supply
- Electronic automotive equipment such as Engine controls, Panels and Audio systems.
- Electric musical instrument, and other digital devices
- Above equipment of Power line and High speed signal line.

### ■ Type: EXCCL

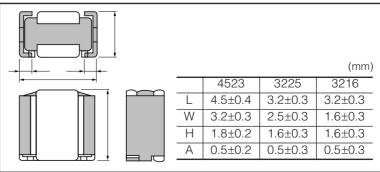
Explanation of Part Numbers



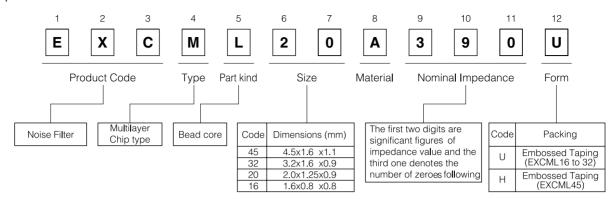
### ■ Construction



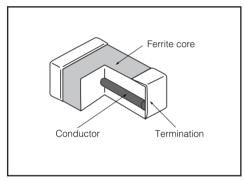
# ■ Dimensions in mm (not to scale)



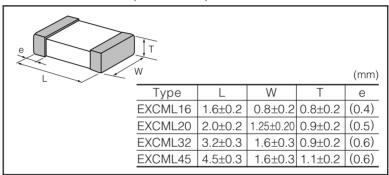
- Type: EXCML
- Explanation of Part Numbers



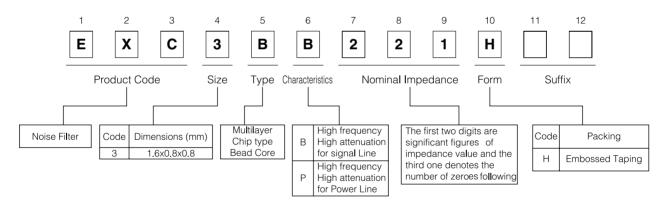
### ■ Construction



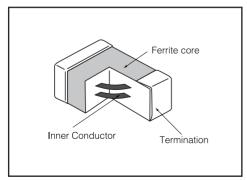
### ■ Dimensions in mm (not to scale)



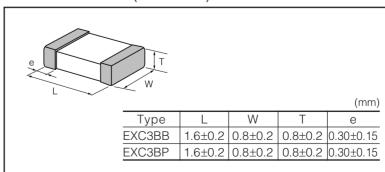
- Type: EXC3B
- Explanation of Part Numbers



### ■ Construction



### ■ Dimensions in mm (not to scale)



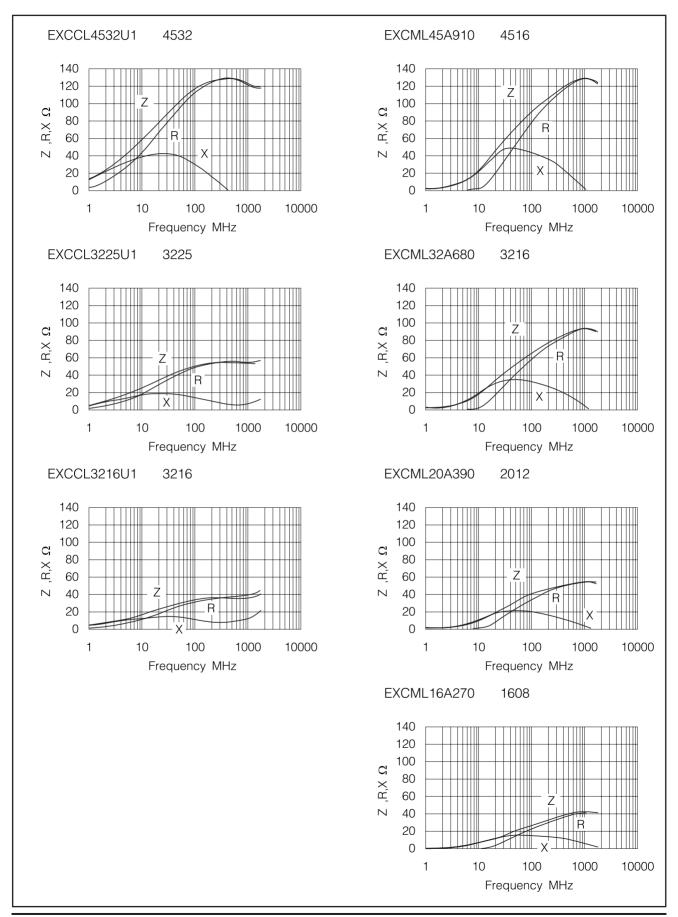
# ■ Ratings

Туре	Part Number	Impedan	ce	Rated Current	DC Resistance
туре	ran Number	(Ω) at 100 MHz	tol.(%)	(mA DC)	(Ω) Max.
4532	EXCCL4532U1	115		2000	0.1
3225	EXCCL3225U1	45		2000	0.05
3216	EXCCL3216U1	25		2000	0.05
4516	EXCML45A910H	91		3000	0.016
3216	EXCML32A680U	68		3000	0.012
2012	EXCML20A390U	39	±25	4000	0.008
1608	EXCML16A270U	27		4000	0.006
	EXC3BP600H	60		1000	0.07
	EXC3BP121H	120		500	0.1
1608	EXC3BB221H	220		200	0.3
	EXC3BB601H	600		100	0.8
	EXC3BB102H	1000		50	1

■ Impedance Characteristics (Reference Data)

Measuered by HP4291A

|Z|: Impedance R: Resistance X: Reactance



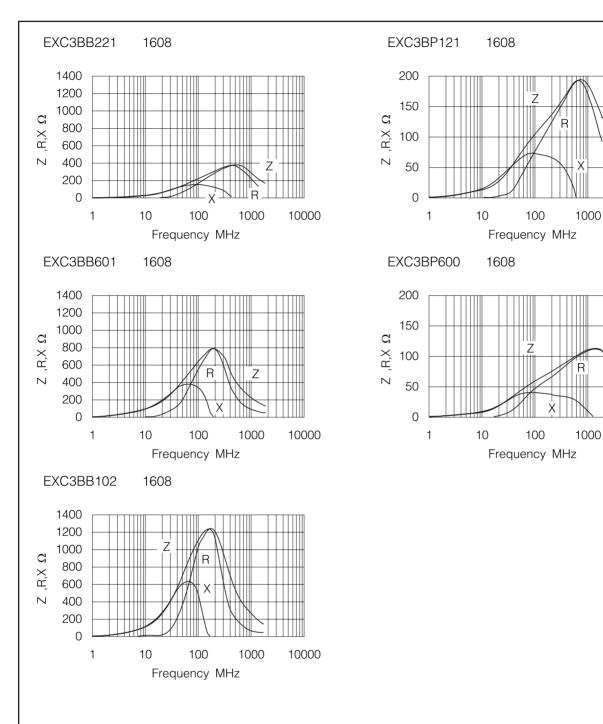
■ Impedance Characteristics (Reference Data)

Measured by HP4291A

|Z|: Impedance R: Resistance X: Reactance

10000

10000

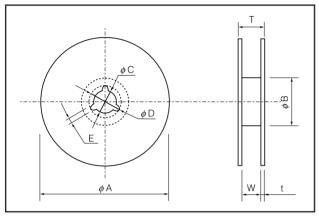


# ■ Packaging Methods

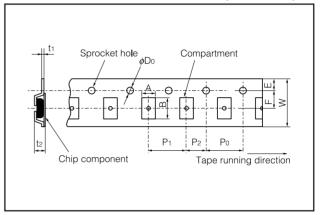
# Standard Quantity

Part Number	Embossed Taping	Weight (mg/pcs.) Reference Data	
EXCCL4532U1	1000 pcs./reel	125.8	
EXCCL3225U1	2000 pcs./reel	60.5	
EXCCL3216U1	2000 pcs./reel	37	
EXCML45A910H	3000 pcs./reel	36.0	
EXCML32A680U	3000 pcs./reel	21.5	
EXCML20A390U	4000 pcs./reel	10.5	
EXCML16A270U	4000 pcs./reel	4.5	
EXC3B H	4000 pcs./reel	4.5	

## Standard Reel Dimensions in mm



## Embossed Carrier Dimensions in mm (not to scale)



### Standard Reel Dimensions (mm)

Part Number	φΑ	<i>φ</i> Β	φC	φD	Е	W	Т	t
EXCCL4532U1						13.0+0.5	16.5 max.	
EXCCL3225U1						Q 5+0.5	13 max.	
EXCCL3216U1						$9.5^{+0.5}_{-1.0}$	13 IIIax.	
EXCML45A910H	180.0_3.0	60.0±1.0	13.0±0.5	21.0±0.8	2.0±0.5	13.0+0.5	16.5 max.	1.2±0.5
EXCML32A680U								
EXCML20A390U						O 5+0.5	13 max.	
EXCML16A270U						$9.5^{+0.5}_{-1.0}$	is illax.	
EXC3B								

# Embossed Carrier Dimensions (mm)

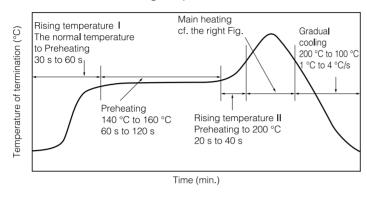
Part Number	А	В	W	F	Е	P <sub>1</sub>	P <sub>2</sub>	P <sub>0</sub>	$\phi D_0$	t <sub>1</sub>	t <sub>2</sub>
EXCCL4532U1	3.6±0.2	4.9±0.2	12.0±0.2	5.5±0.1		8.0±0.1					2.4 max.
EXCCL3225U1	2.9±0.2	3.6±0.2	8 0+0 3	3.5±0.1							2.1 max.
EXCCL3216U1	2.0±0.2	3.6±0.2	0.010.2	3.5±0.1							2.1 max.
EXCML45A910H	1.9±0.2	4.8±0.2	12.0±0.2	5.5±0.1	1.75±0.10	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1	0.20±0.05	1.8 max.
EXCML32A680U	1.9±0.2	3.5±0.2									
EXCML20A390U	1.5±0.2	2.3±0.2	8.0±0.2	3.5±0.1							1.6 max.
EXCML16A270U	1.1±0.2	2.1±0.2									i.o max.
EXC3B	1.0±0.1	1.8±0.1								0.25±0.05	

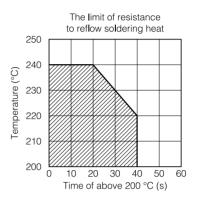
### ■ Soldering Conditions

Precautions and recommendations are described below.

- Please inquire with us when different conditions are used.
- Please measure a temperature of terminations and study the solderability of every type of board, before actual use.

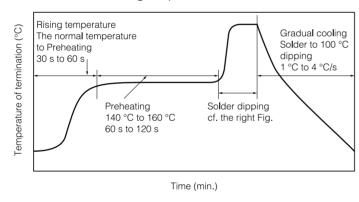
#### < Recommended reflow soldering temperature >

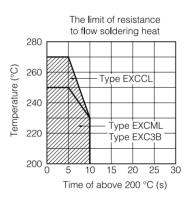




\* Reflow soldering shall be within two times

#### < Recommended flow soldering temperature>



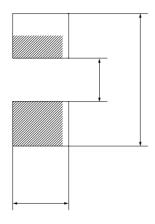


<Repair with hand soldering>

• Use a soldering iron with tip temperature 350 °C or less. Solder for 3 seconds or less for each termination.

(mm)

# ■ Recommended Land Pattern Dimensions in mm (not to scale)



Part Number	Flow/Reflow	А	В	С
EXCCL4532U1		3	5.4	2.8
EXCCL3225U1		1.7	4.1	2.1
EXCCL3216U1	Flow, Reflow	1.7	4.1	1.2
EXCML45A910H		2.6 to 3	5.5 to 6.5	1.2 to 1.6
EXCML32A680U		1.6 to 2	4 to 5	1.2 to 1.6
EXCML20A390U		0.8 to 1.2	3 to 4	1 to 1.2
EXCML16A270U		0.6 to 1	2 to 3	0.8 to 1
EXC3B	Flow	0.8 to 1	2.4 to 3	0.6 to 0.8
EVOOR	Reflow	0.8 to 1	2 to 2.6	0.8 to 1

## **≜** Safety Precautions

- 1. Flux: Use rosin or non-halogen type flux.
- 2. Cleaning agent: Use alcohol type. Inquire for other type of cleaning agent.
- 3. Excessive mechanical stress may damage the components. Take care in handling.
- 4. Store at temperature of –5 °C to +40 °C and relative humidity 40 % to 60 %. Avoid rapid changes of temperature and humidity.
- 5. Use the components within one year after date of inspection for shipment.
- 6. This catalog shows the quality and performance of a unit component. For quality assurance, exchange the delivery specification with us. Before adoption, be sure to evaluate and verify the product by mounting it in your product.